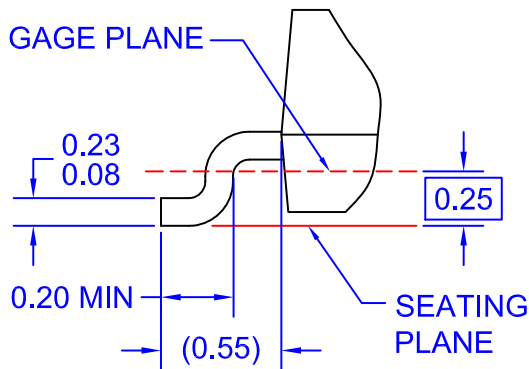
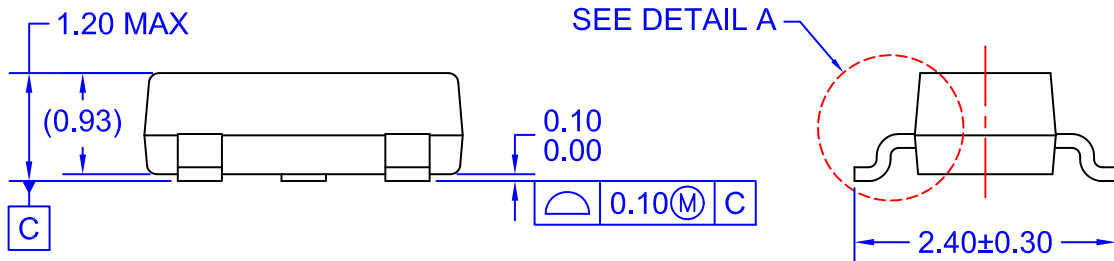
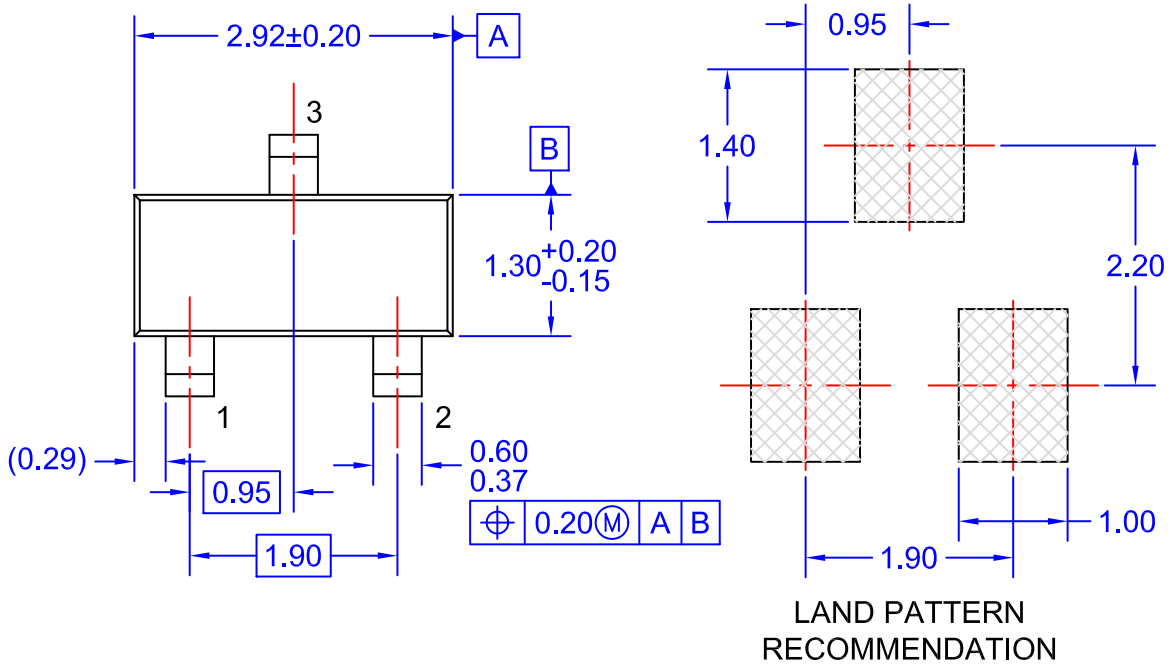




**SOT-23**  
**CASE 318BM**  
**ISSUE O**

DATE 31 AUG 2016



**DETAIL A**  
 SCALE: 2X

**NOTES: UNLESS OTHERWISE SPECIFIED**

- A) REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE INCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 2009.

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